



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

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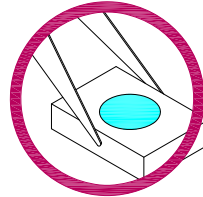


Handling Precautions

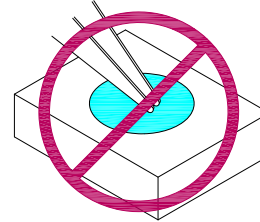
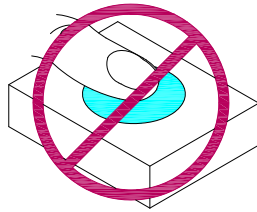
Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.

As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

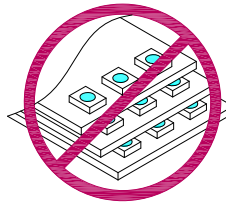
1. Handle the component along the side surfaces by using forceps or appropriate tools.



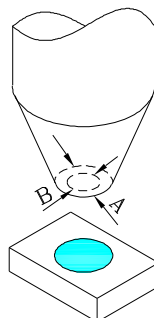
2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.



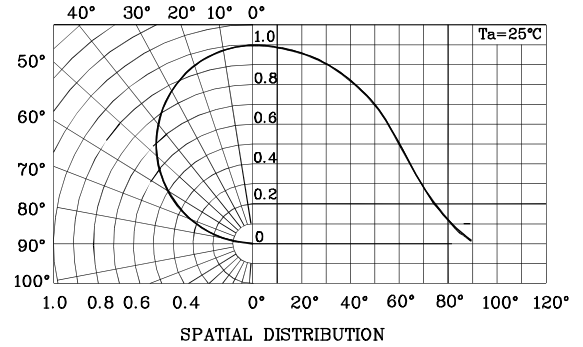
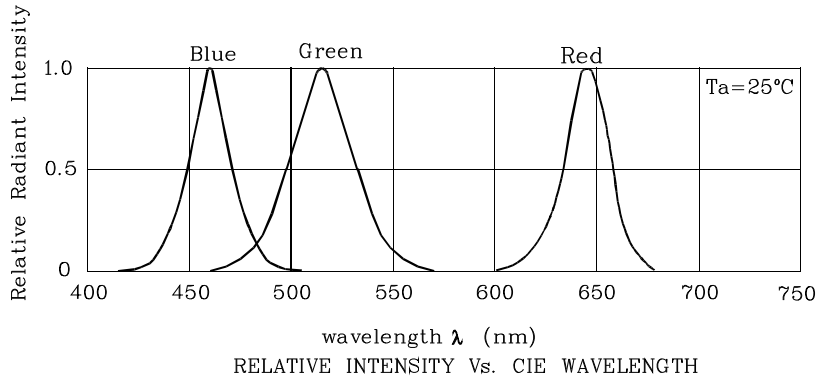
3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



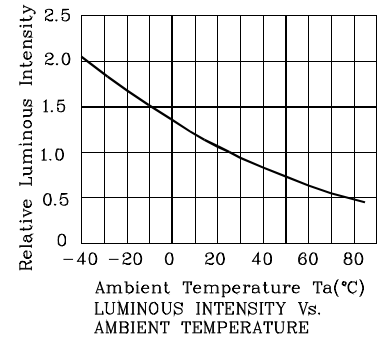
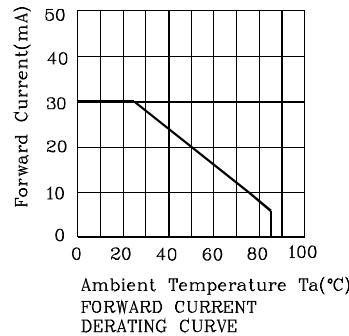
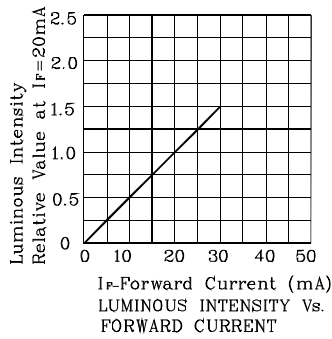
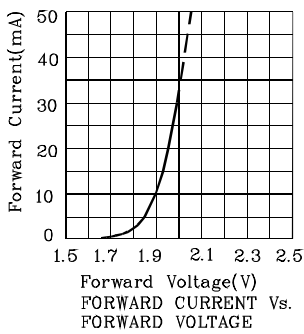
- 4.1. The inner diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks.
- 4.2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 4.3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



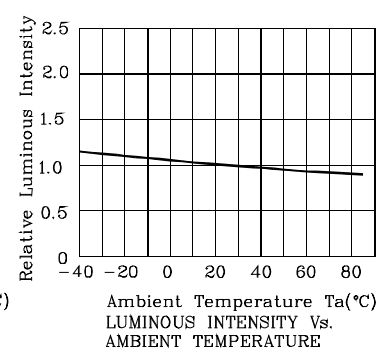
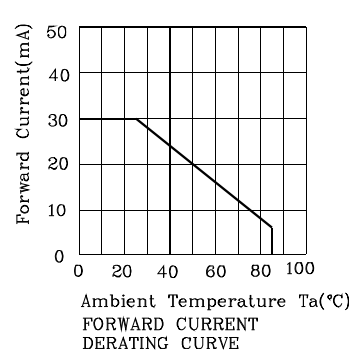
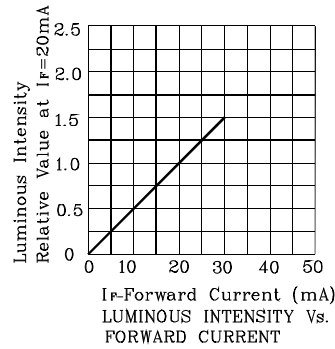
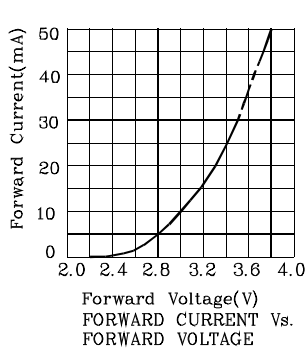
5. As silicone encapsulation is permeable to gases, some corrosive substances such as H₂S might corrode silver plating of lead-frame. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.



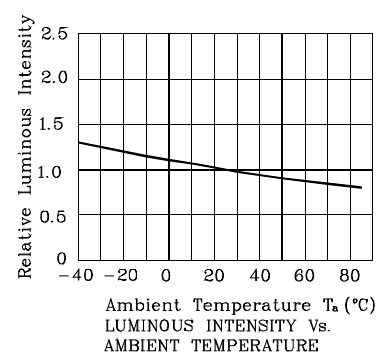
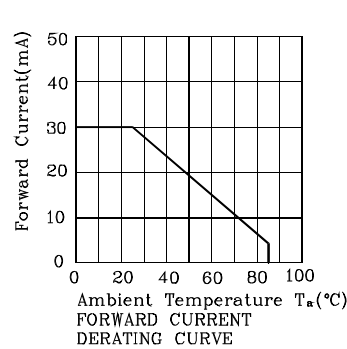
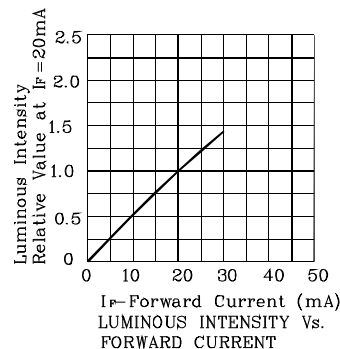
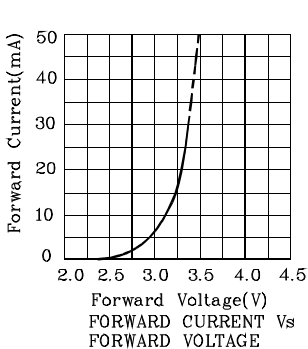
◆ Red



◆ Blue



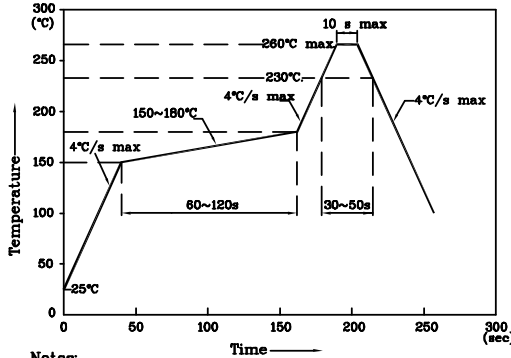
◆ Green



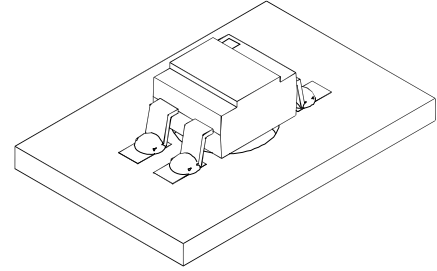
LED is recommended for reflow soldering and soldering profile is shown below.

❖ The device has a single mounting surface. The device must be mounted according to the specifications.

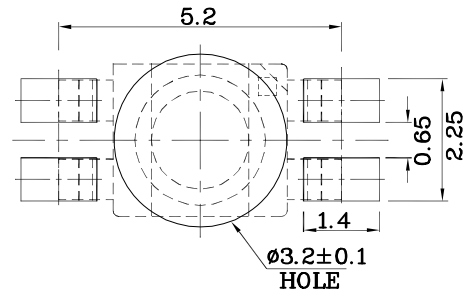
Reflow Soldering Profile for SMD Products (Pb-Free Components)



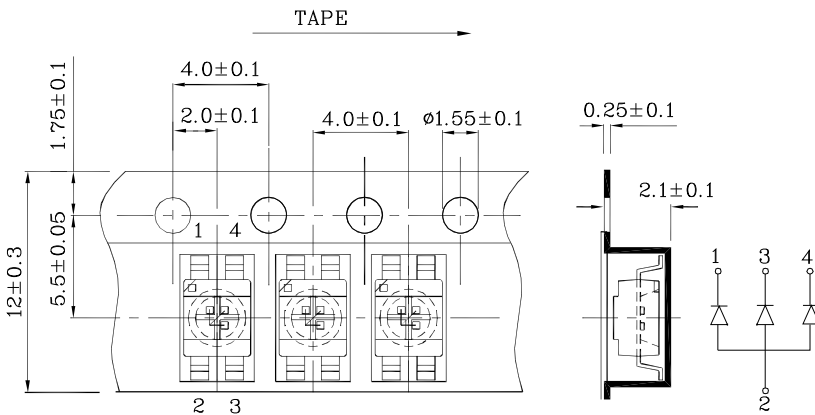
- Notes:
1. Maximum soldering temperature should not exceed 260°C
 2. Recommended reflow temperature: 145°C-260°C
 3. Do not put stress to the epoxy resin during high temperatures conditions



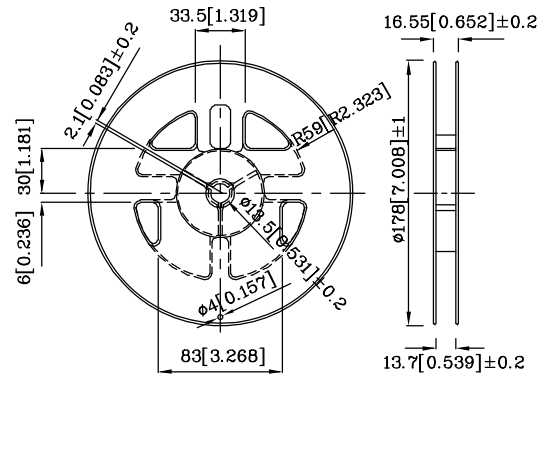
❖ Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



❖ Tape Specification (Units : mm)



❖ Reel Dimension



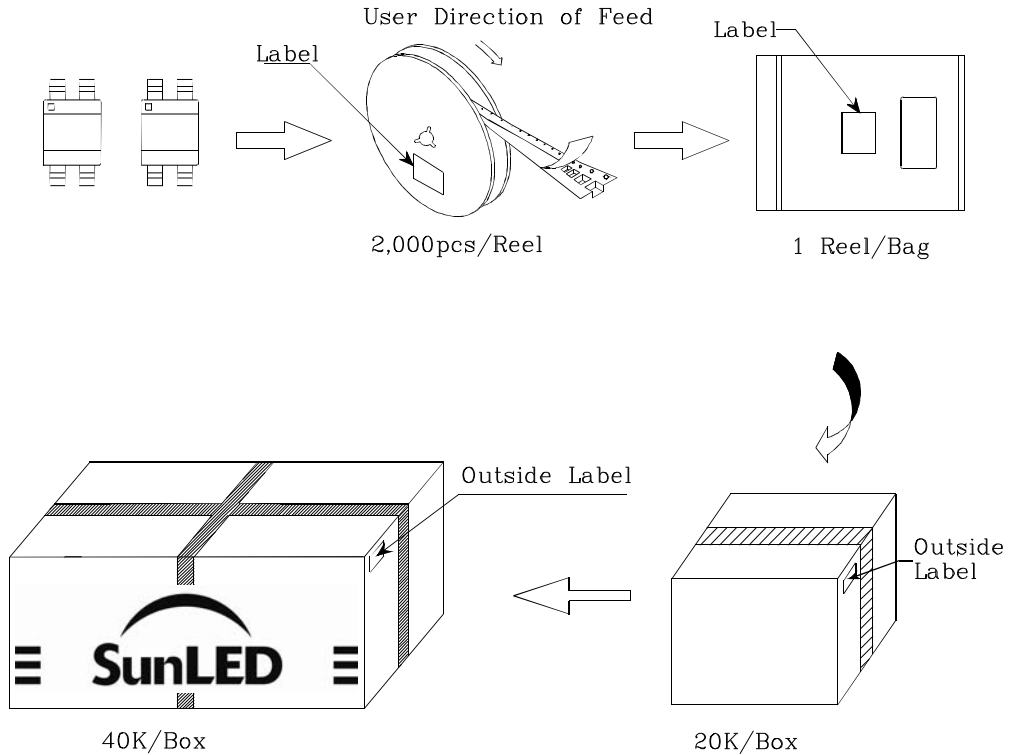
Remarks:


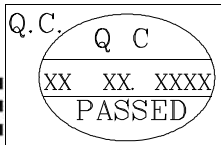

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous intensity / luminous flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

PACKING & LABEL SPECIFICATIONS



		
P/NO : XZxxx45x-9		
QTY : 2000 pcs	CODE: XXX	
S/N : XX		
LOT NO :		
		
RoHS Compliant		

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